
信頼性試験データ
Reliability test data

コモンモードノイズフィルタアレイ
Common mode Noise Filter Array

EXC28CG***U

検印 Check	担当 Design
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1. 寿命試験

Life Test

1-1. 温度サイクル試験

Thermal Shock Test

試験条件 (1cycle)

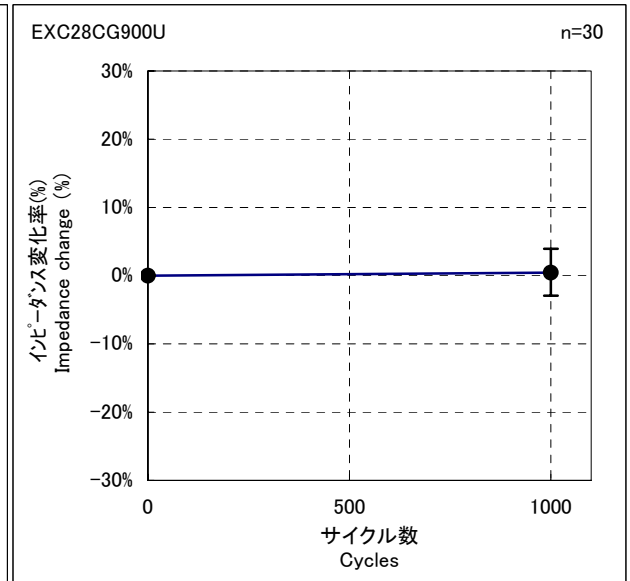
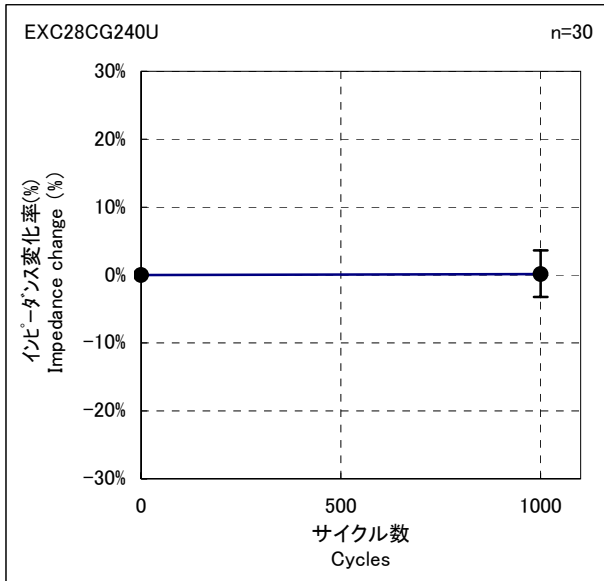
温度 -40°C(30分)~+85°C(30分)

Test condition: (1cycle)

Temp. -40°C(30min.) to +85°C (30min.)

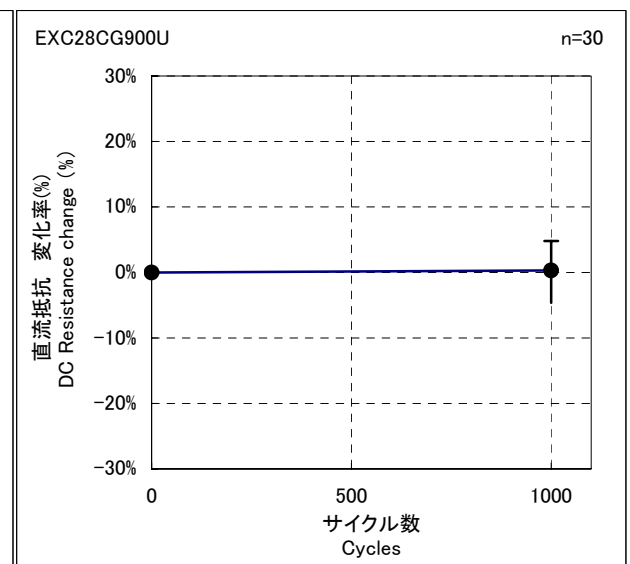
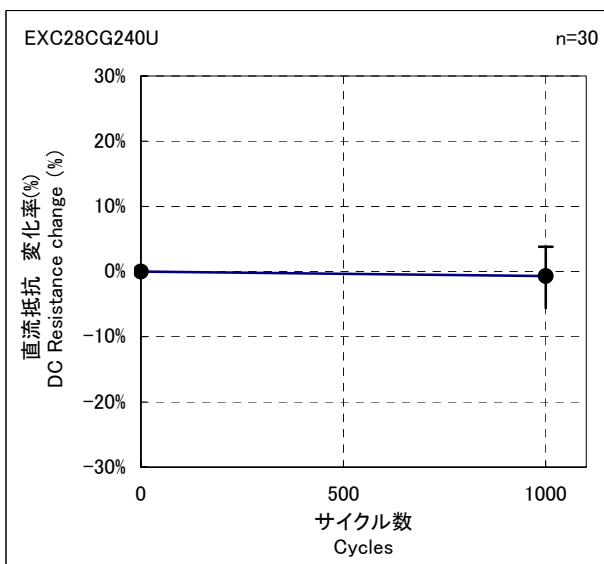
1.インピーダンス変化率

1.Impedance change



2. 直流抵抗 変化率

2. DC Resistance Change



3.機械的損傷無し

3.No evidence of mechanical damage : OK

1-2. 高温負荷寿命試験
Load Life Test

試験条件

温度 85±2°C

印加電流 定格電流(150mA)

Test condition:

Temp.

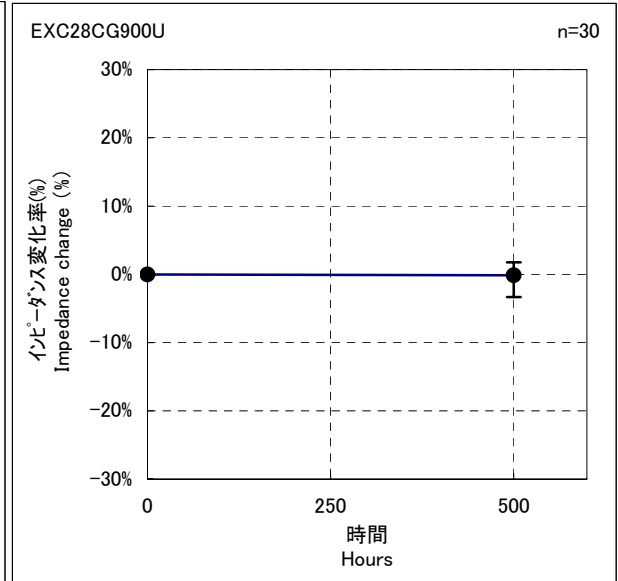
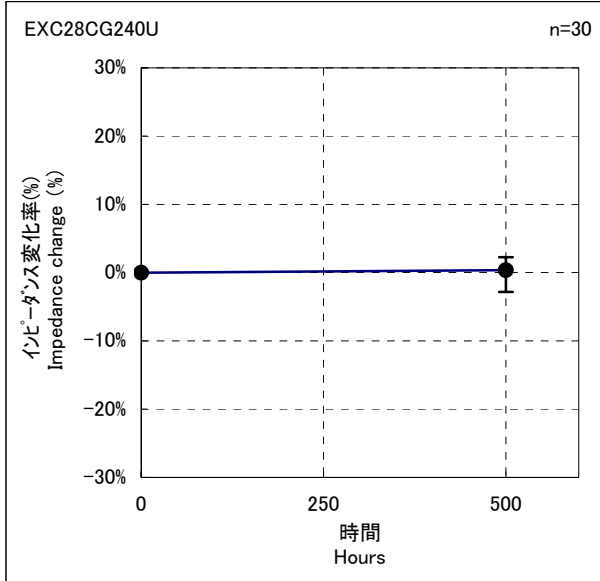
Applied current

85±2°C

Rated current (150mA)

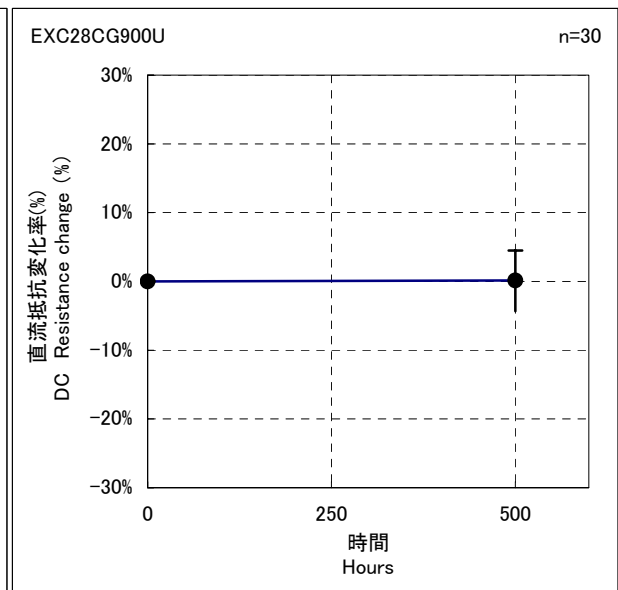
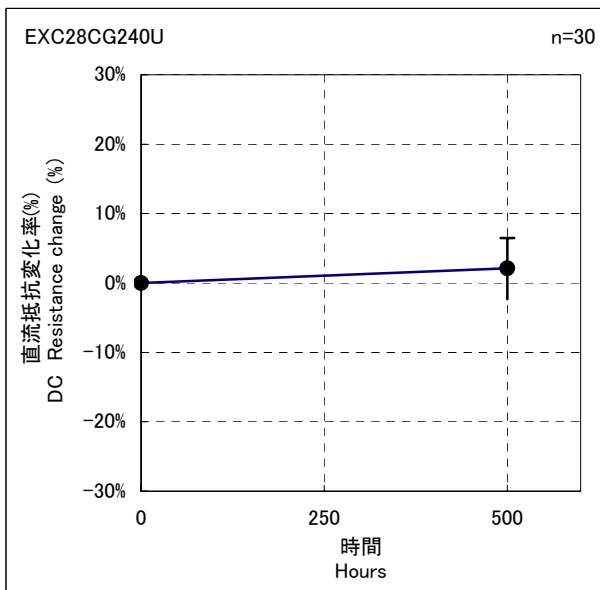
1.インピーダンス変化率

1.Impedance change



2. 直流抵抗 変化率

2. DC Resistance Change



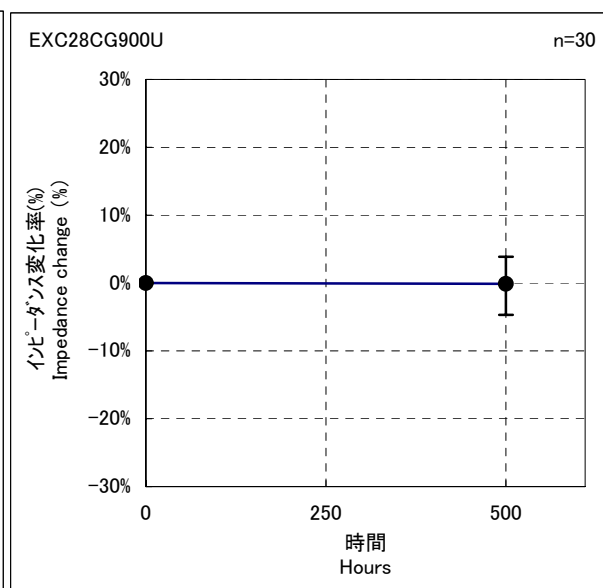
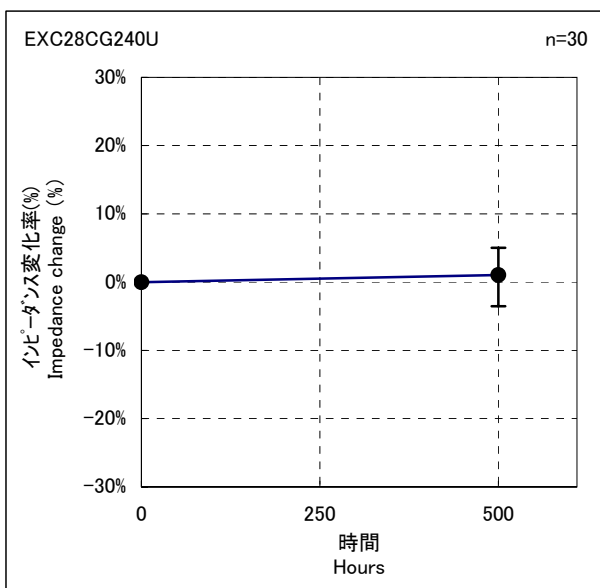
3.機械的損傷無し

3.No evidence of mechanical damage: OK

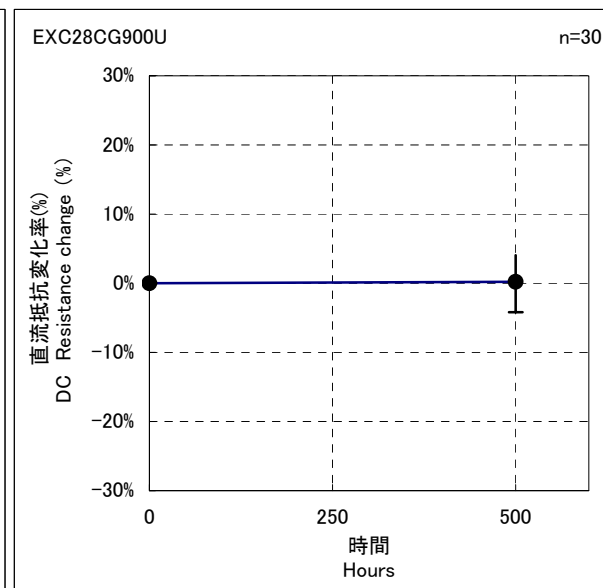
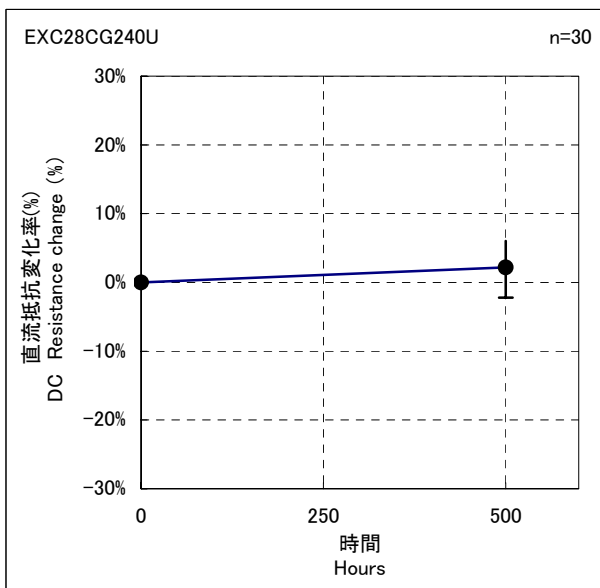
1-3. 耐湿負荷寿命試験 Humidity Load Life Test

試験条件	Test condition:	
温度 40±2°C	Temp.	40±2°C
湿度 90~95%	Humidity	90 to 95%
印加電流定格電流(150mA)	Applied current	Rated current(150mA)

1.インピーダンス変化率 1.Impedance change



2. 直流抵抗 変化率 2. DC Resistance Change



1-4. 耐湿性
Humidity Test

試験条件

温度 40±2°C

湿度 90~95%

Test condition:

Temp.

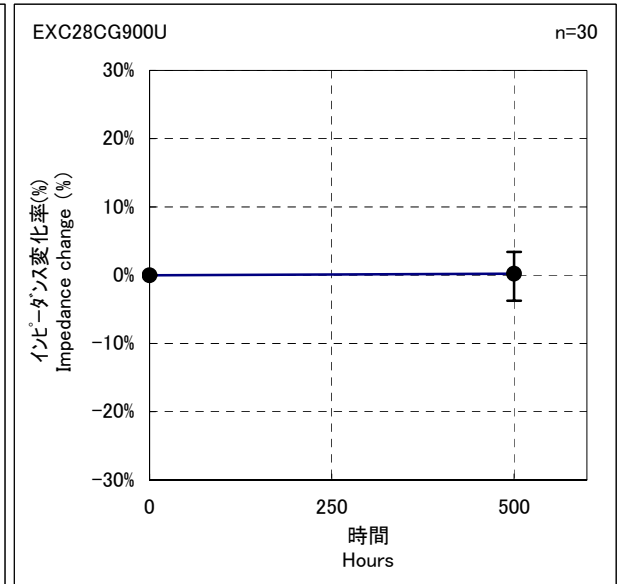
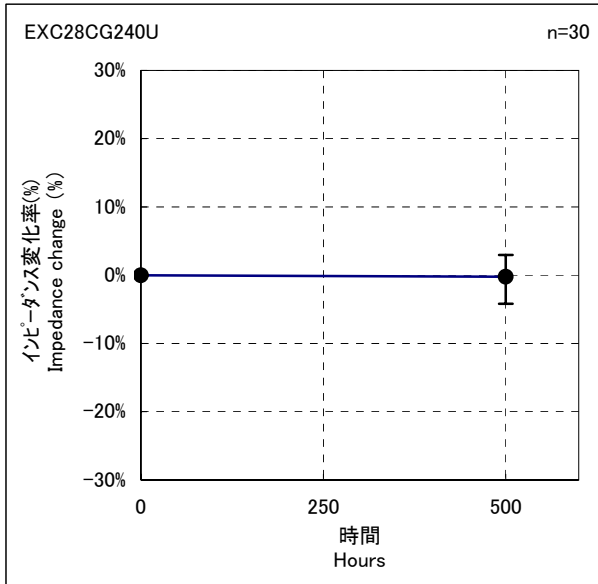
Humidity

40±2°C

90 to 95%

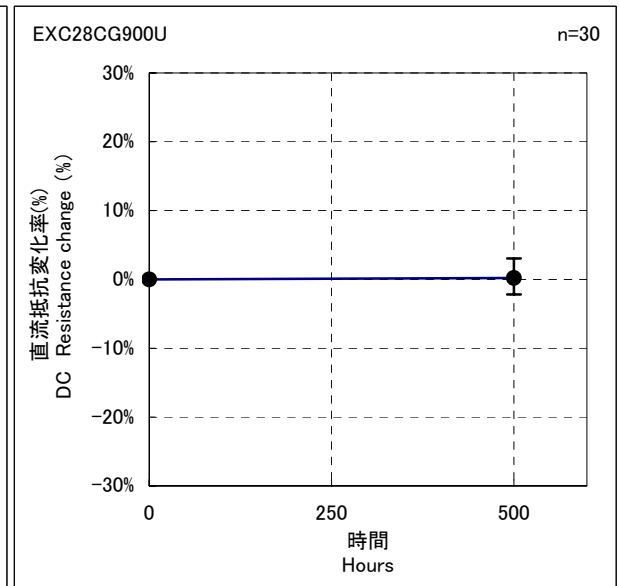
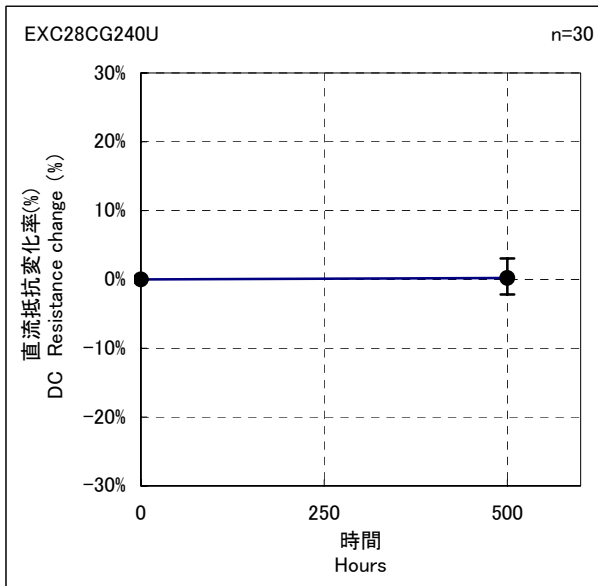
1.インピーダンス変化率

1.Impedance change



2. 直流抵抗 変化率

2. DC Resistance Change



3.機械的損傷無し

3.No evidence of mechanical damage: OK

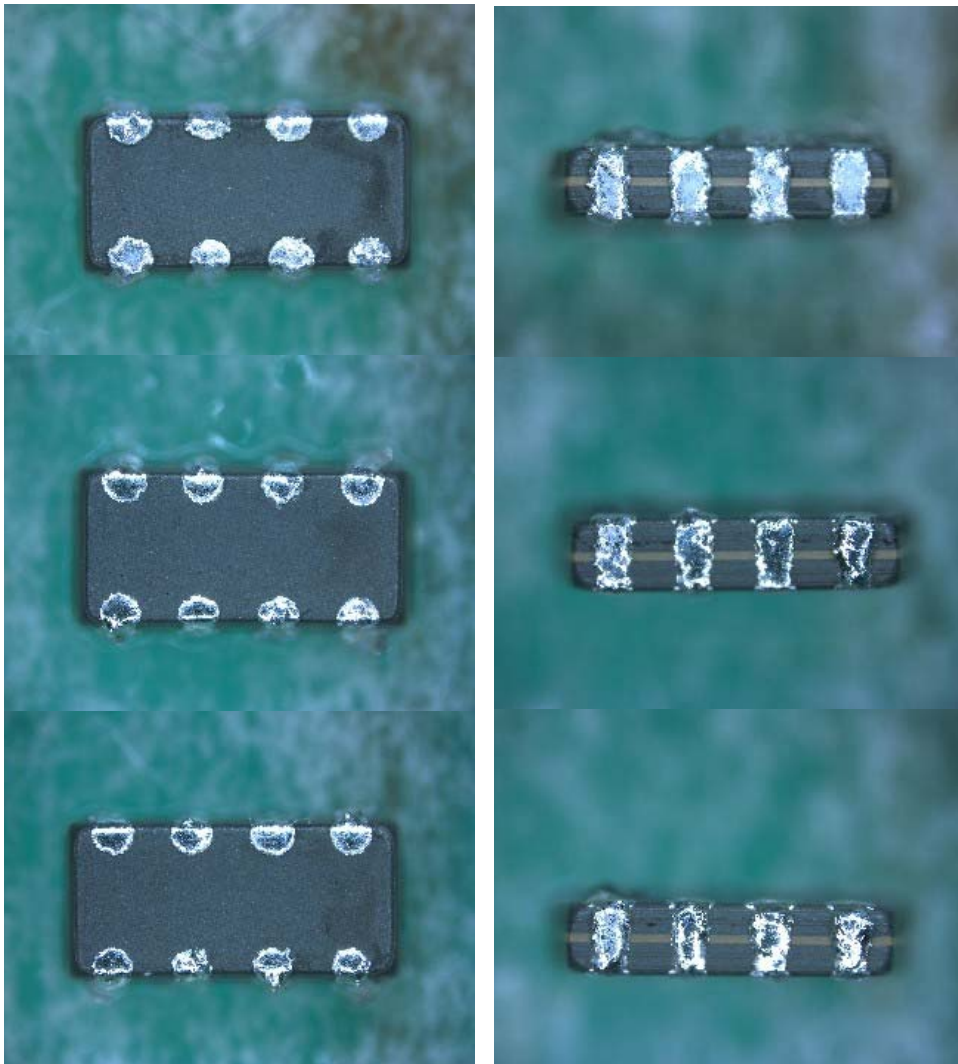
2. 機械的試験 Mechanical Test

2-1. はんだ付け性 Solderability Test

試験条件
温度 $230 \pm 5^{\circ}\text{C}$
浸漬時間 4 ± 0.5 秒

Test condition:
Temp. $230 \pm 5^{\circ}\text{C}$
Duration 4 ± 0.5 sec

n=30 pieces



電極の90%以上新しいはんだで覆われている

At least 90% of terminal electrode is covered by new solder:OK

2-2. はんだ耐熱試験 Resistance to soldering

試験条件

温度 260±5°C

時間 10±0.5sec.

Test condition:

Temp.

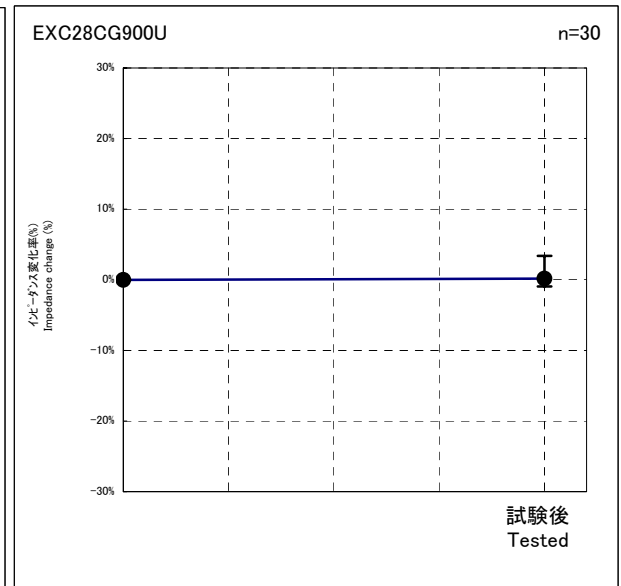
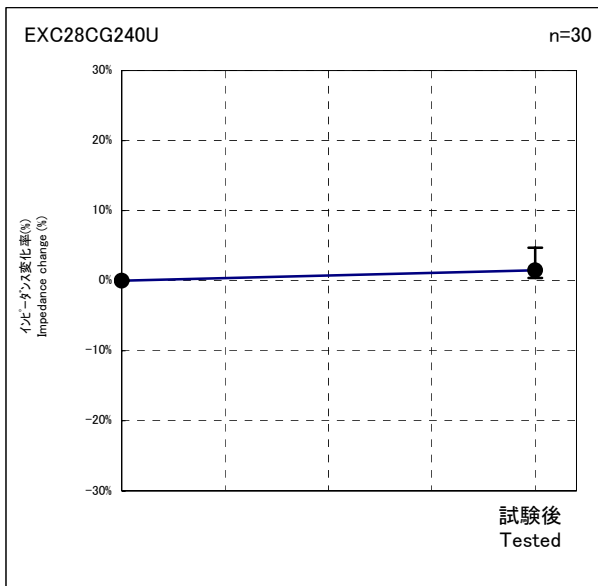
Duration

260±5°C

10±0.5sec.

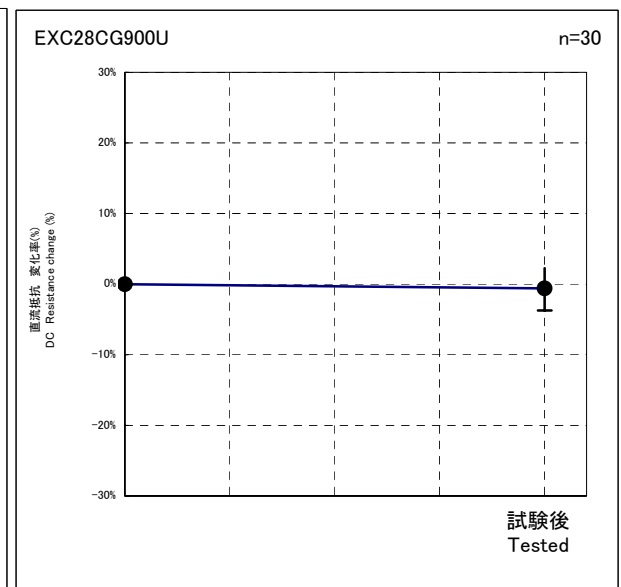
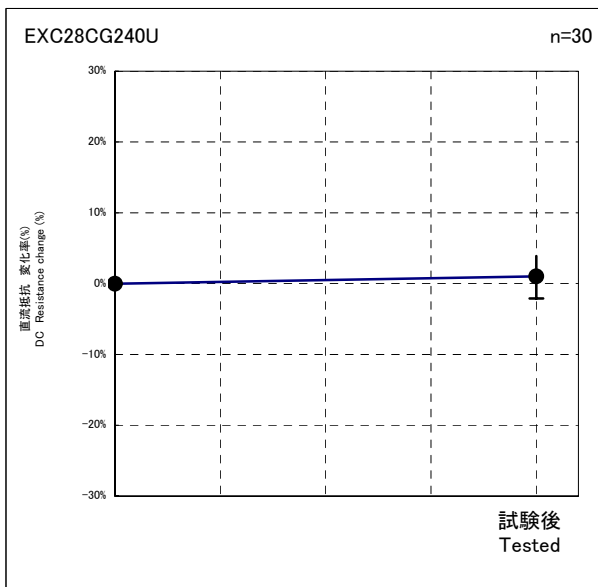
1.インピーダンス変化率

1.Impedance change



2. 直流抵抗 変化率

2. DC Resistance Change



3.機械的損傷無し

3.No evidence of mechanical damage: OK

2-3. たわみ試験 Bending Test

試験条件

Test condition:

試験基板ガラスエポ

Testing board

Glass epoxy

(厚み t=1.0mm)

(thickness 1.0mm)

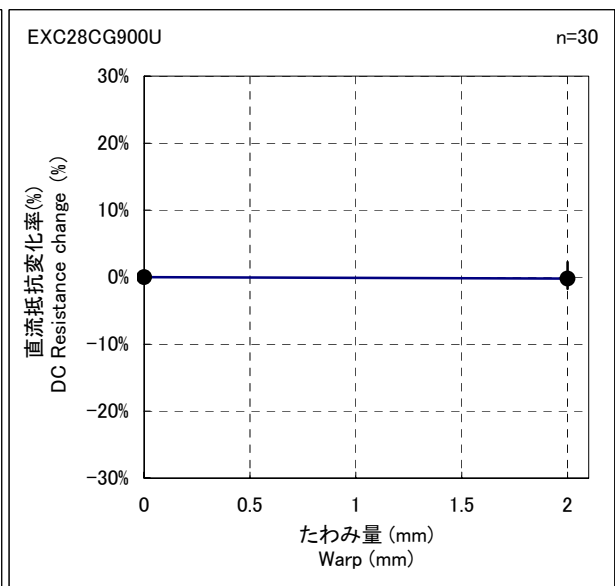
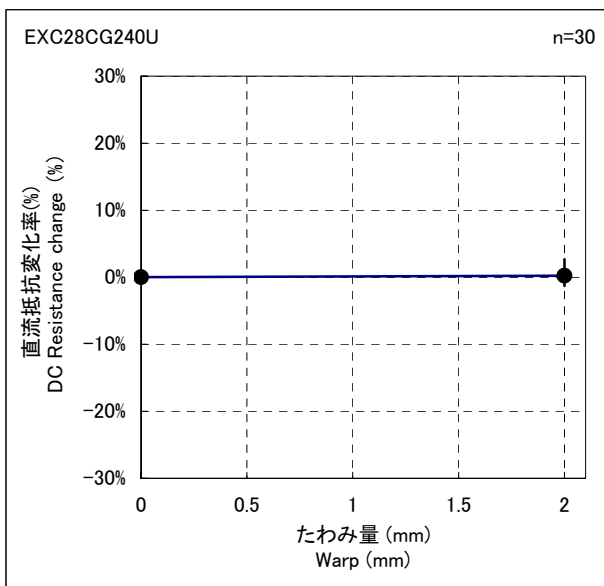
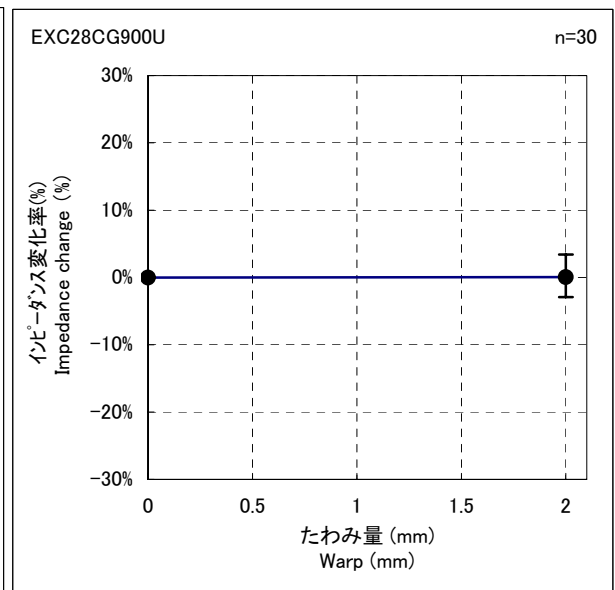
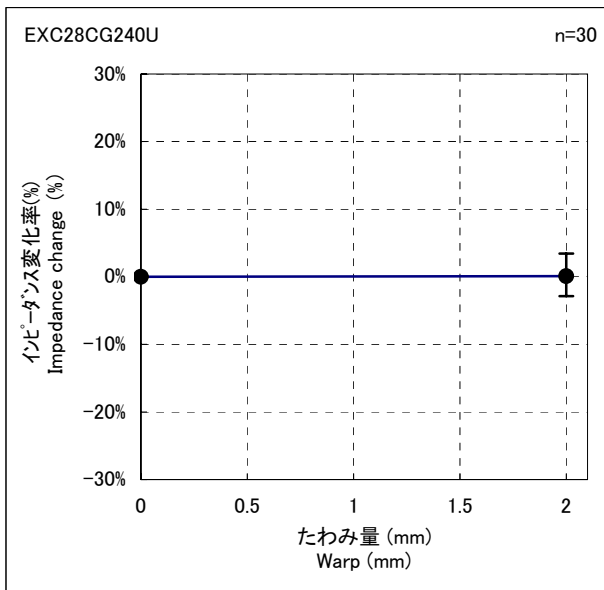
たわみ量2mm

Warp

2mm

インピーダンス変化率

Impedance change



3.機械的損傷無し

3.No evidence of mechanical damage: OK

2-4. 振動試験

Vibration Test

試験条件

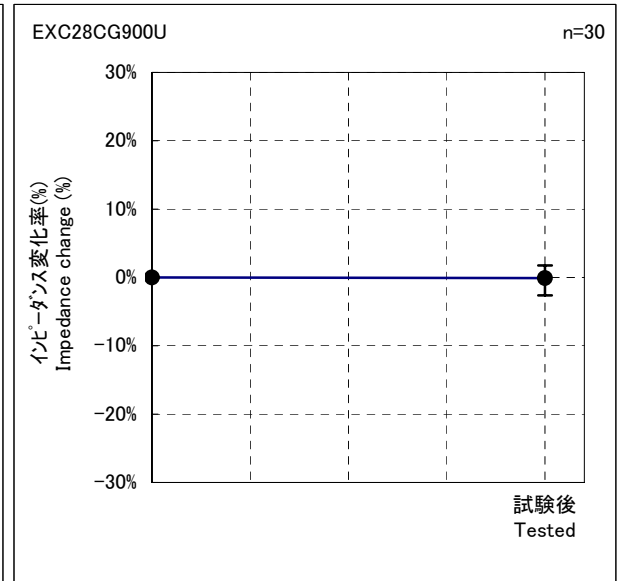
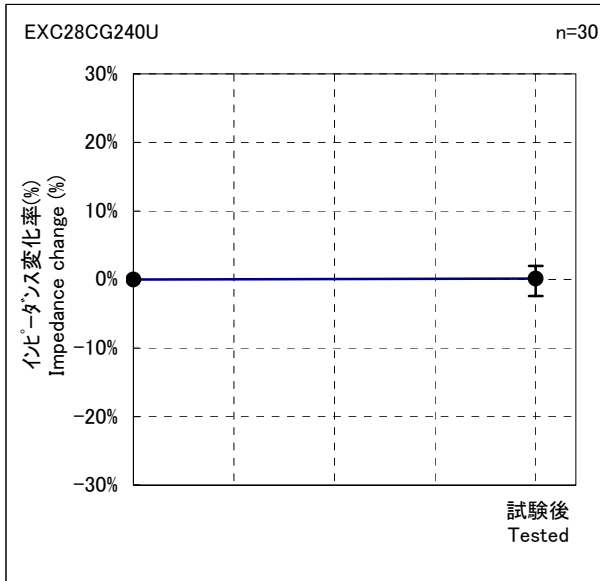
試験周波 10→55→10Hz
(1分間で往復)
X, Y, Z 各2時間

Test condition:

Testing Freq
10 to 55 to 10Hz
(Sweep time 1 min.)
X, Y, Z each 2 hours

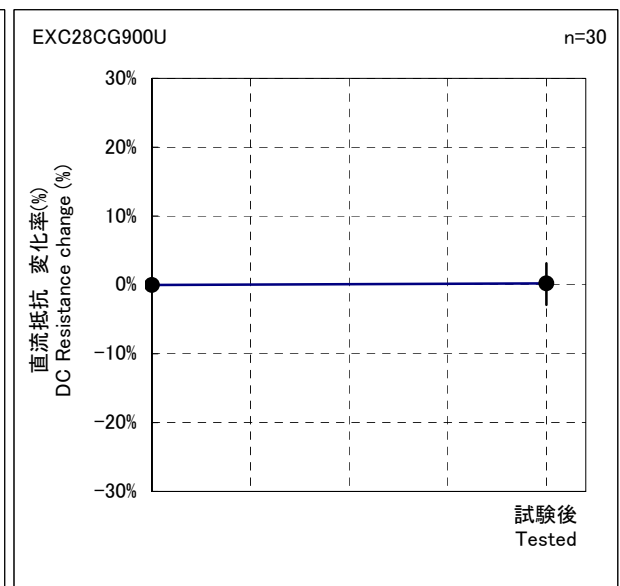
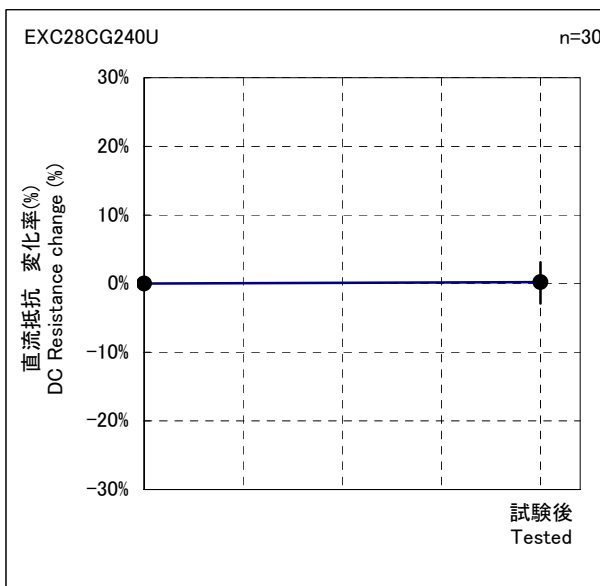
1.インピーダンス変化率

1.Impedance change



2. 直流抵抗 変化率

2. DC Resistance Change



3.機械的損傷無し

3.No evidence of mechanical damage: OK